

Features

- Advanced Shield Gate Trench technology
- Super Low Gate Charge
- High-Speed Switching
- 100% EAS Guaranteed
- Green Device Available

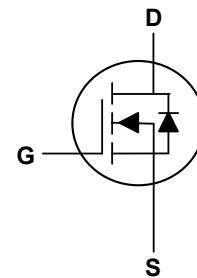
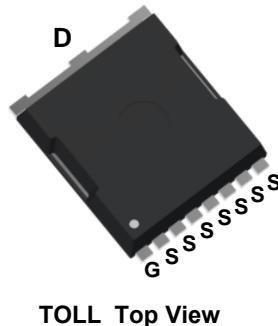
Product Summary



V_{DS}	100	V
I_D	300	A
$R_{DS(ON)}$ Typ (at $V_{GS}=10V$)	1.0	mΩ
$R_{DS(ON)}$ Typ (at $V_{GS}=4.5V$)	1.3	mΩ

Applications

- High Frequency Point-of-Load,Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



Absolute Maximum Ratings($T_c=25^\circ C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	$I_D @ T_c = 25^\circ C$	300	A
Continuous Drain Current ¹	$I_D @ T_c = 100^\circ C$	282	A
Pulsed Drain Current ²	I_{DM}	1200	A
Single Pulse Avalanche Energy ³	E_{AS}	2592	mJ
Total Power Dissipation ⁴	P_D	500	W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	---	40	°C/W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	---	0.25	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100	---	---	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=30\text{A}$	---	1.0	1.2	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$	---	1.3	2.0	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	2.0	---	4.0	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=80\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	---	---	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
Total Gate Charge	Q_g	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=30\text{A}$	---	280	---	nC
Gate-Source Charge	Q_{gs}		---	73	---	
Gate-Drain Charge	Q_{gd}		---	85	---	
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=10\text{V}, R_G=3.9\Omega, I_{\text{D}}=30\text{A}$	---	36	---	ns
Rise Time	T_r		---	85	---	
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$		---	182	---	
Fall Time	T_f		---	113	---	
Input Capacitance	C_{iss}	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	13765	---	pF
Output Capacitance	C_{oss}		---	2155	---	
Reverse Transfer Capacitance	C_{rss}		---	100	---	

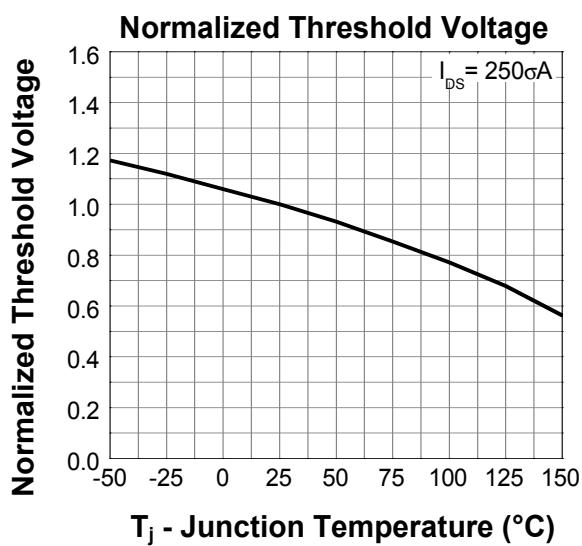
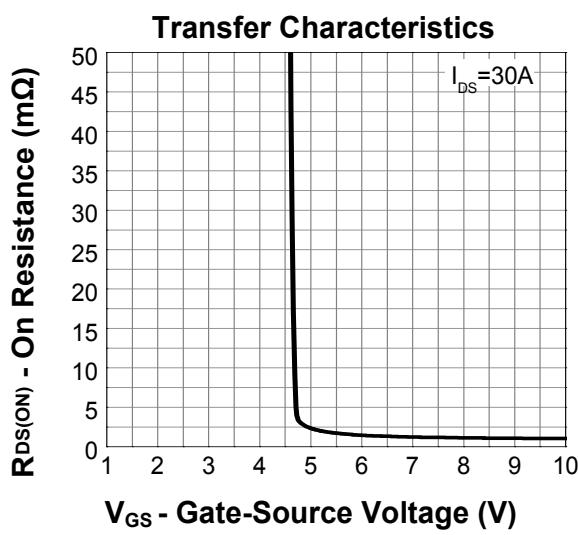
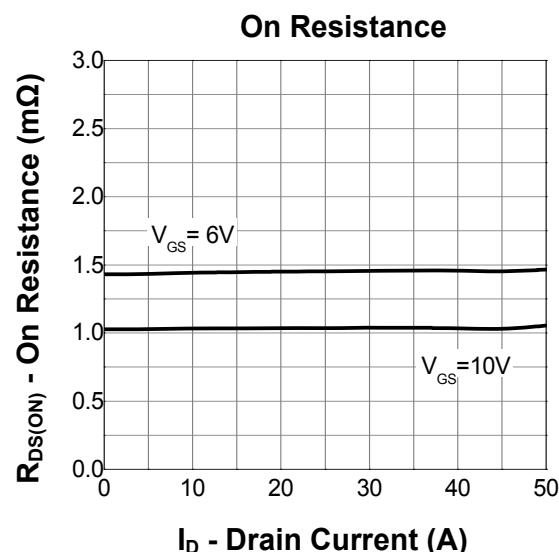
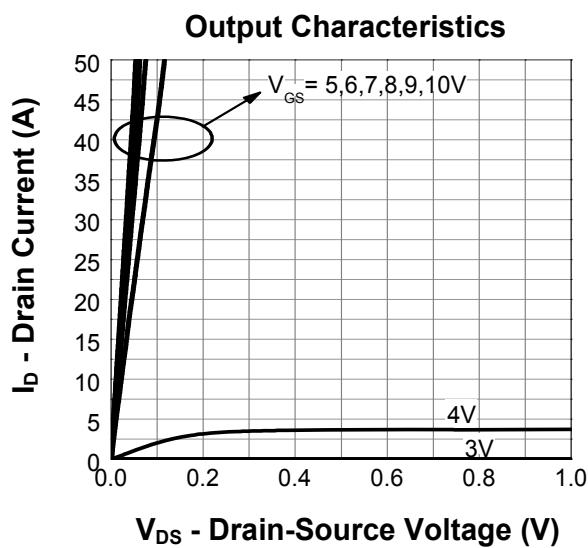
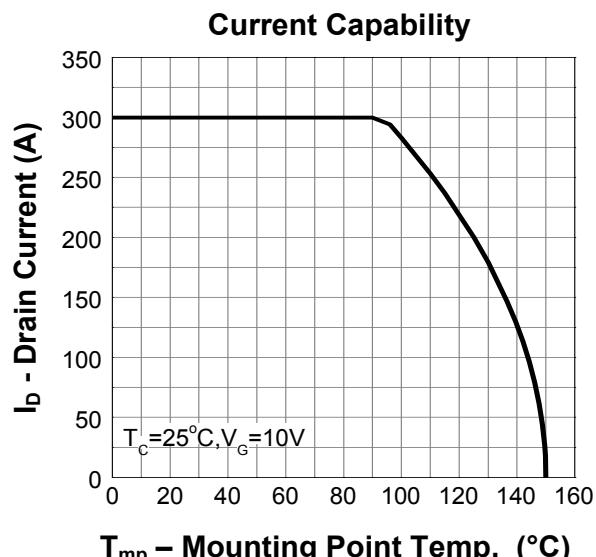
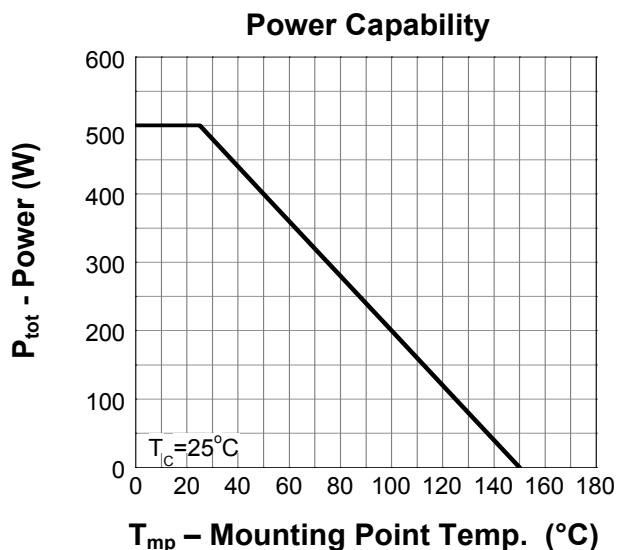
Drain-Source Diode Characteristics

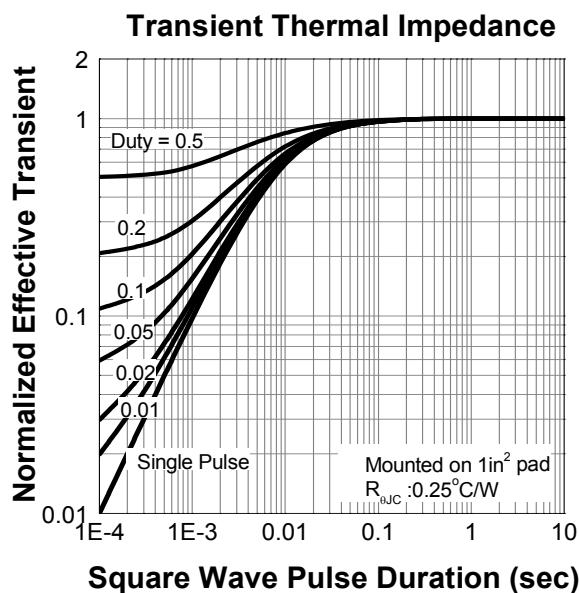
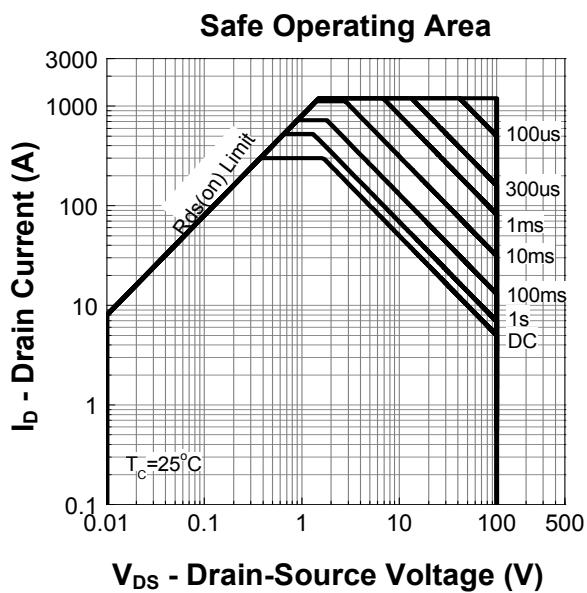
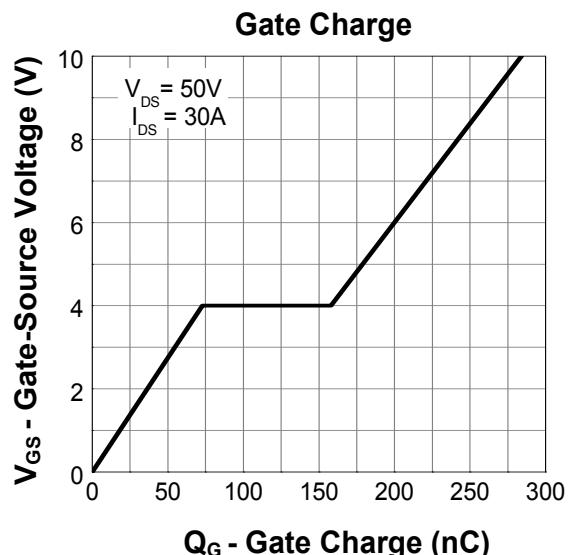
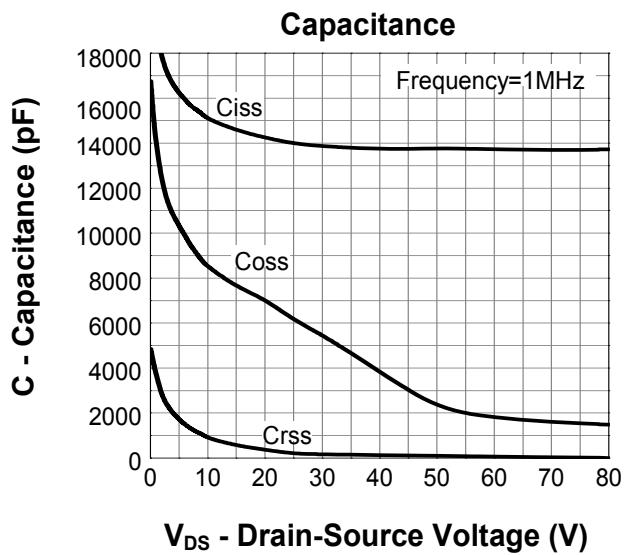
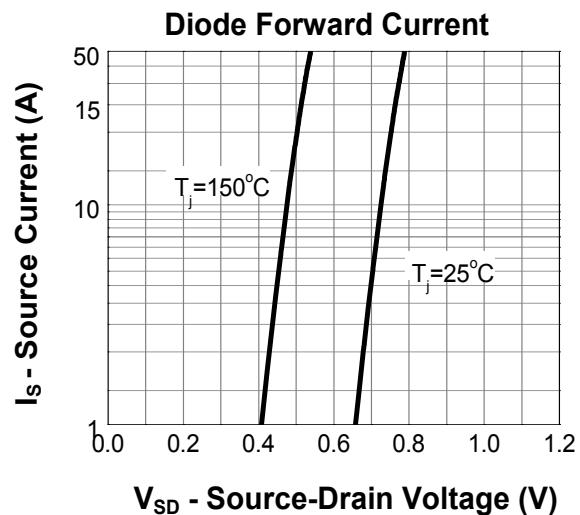
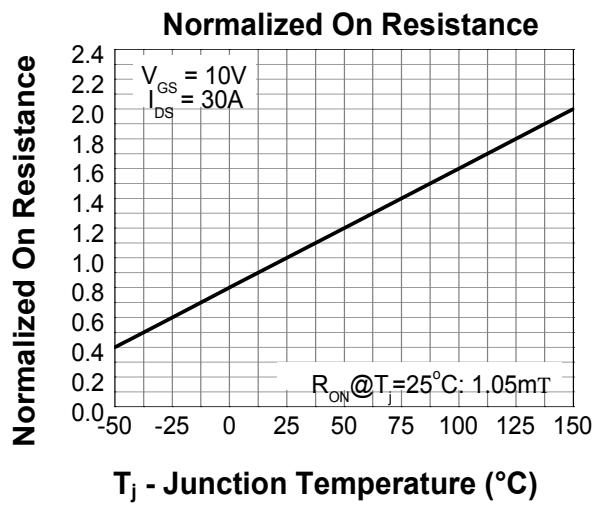
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode Forward Voltage ²	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=30\text{A}, T_J=25^\circ\text{C}$	---	---	1.3	V
Reverse recovery time	t_{rr}	$I_F=30\text{A}, \frac{dI}{dt}=100\text{A}/\mu\text{s}$	---	121	---	ns
Reverse recovery charge	Q_{rr}		---	405	---	nC

Note:

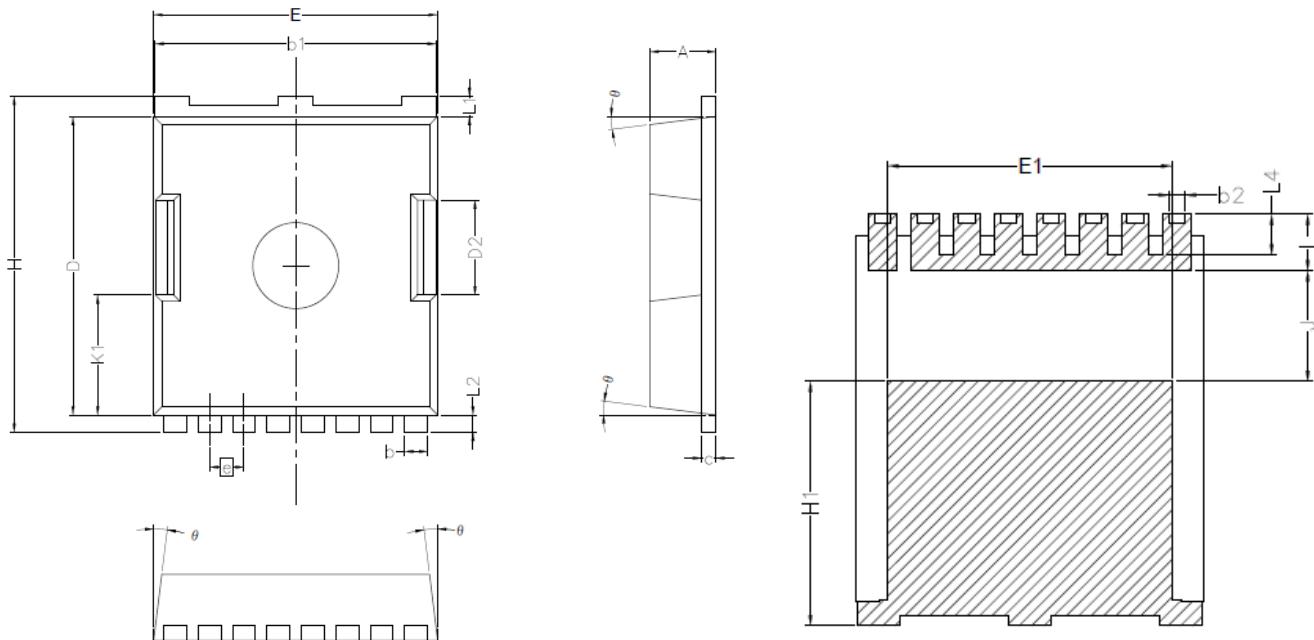
- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=50\text{V}, L=1.0\text{mH}$

Typical Characteristics





TOLL Package Outline Dimensions



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	2.20	2.40
b	0.90	0.90
b1	9.70	9.90
b2	0.42	0.50
c	0.40	0.60
D	10.28	10.58
D2	3.10	3.50
E	9.70	10.10
E1	7.90	8.30
e	1.20BSC	
H	11.48	11.88
H1	6.75	7.15
N	8	
J	3.00	3.30
K1	3.98	4.38
L	1.40	1.80
L1	0.60	0.80
L2	0.50	0.70
L4	1.00	1.30
θ	4°	10°

Printing Information

ATC =====Brand

XXXXXXX =====Material Code

XXYY =====XX Representative Year
YY Representative Weeks